



MICROCHIP TC4426A/TC4427A/TC4428A

1.5A Dual High-Speed Power MOSFET Drivers

Features:

- High Peak Output Current – 1.5A
- Wide Input Supply Voltage Operating Range:
 - 4.5V to 18V
- High Capacitive Load Drive Capability – 1000 pF in 25 ns (typ.)
- Short Delay Times – 30 ns (typ.)
- Matched Rise, Fall and Delay Times
- Low Supply Current:
 - With Logic '1' Input – 1 mA (typ.)
 - With Logic '0' Input – 100 μ A (typ.)
- Low Output Impedance – 7 Ω (typ.)
- Latch-Up Protected: Will Withstand 0.5A Reverse Current
- Input Will Withstand Negative Inputs Up to 5V
- ESD Protected – 4 kV
- Pin-compatible with TC426/TC427/TC428 and TC4426/TC4427/TC4428
- Space-saving 8-Pin MSOP and 8-Pin 6x5 DFN Packages

General Description:

The TC4426A/TC4427A/TC4428A are improved versions of the earlier TC4426/TC4427/TC4428 family of MOSFET drivers. In addition to matched rise and fall times, the TC4426A/TC4427A/TC4428A devices have matched leading and falling edge propagation delay times.

These devices are highly latch-up resistant under any conditions within their power and voltage ratings. They are not subject to damage when up to 5V of noise spiking (of either polarity) occurs on the ground pin. They can accept, without damage or logic upset, up to 500 mA of reverse current (of either polarity) being forced back into their outputs. All terminals are fully protected against Electrostatic Discharge (ESD) up to 4 kV.

The TC4426A/TC4427A/TC4428A MOSFET drivers can easily charge/discharge 1000 pF gate capacitances in under 30 ns. These devices provide low enough impedances in both the on and off states to ensure the MOSFET's intended state will not be affected, even by large transients.

Applications:

- Switch Mode Power Supplies
- Line Drivers
- Pulse Transformer Drive

Package Types



TC4426A/TC4427A/TC4428A

Functional Block Diagram



TC4426A/TC4427A/TC4428A

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Supply Voltage	+22V
Input Voltage, IN A or IN B (V _{DD} + 0.3V) to (GND – 5V)	
Package Power Dissipation (T _A ≤ 70°C)	
DFN	Note 2
MSOP	340 mW
PDIP	730 mW
SOIC.....	470 mW

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, over operating temperature range with 4.5V ≤ V _{DD} ≤ 18V.						
Parameters	Sym	Min	Typ	Max	Units	Conditions
Input						
Logic '1', High Input Voltage	V _{IH}	2.4	—	—	V	
Logic '0', Low Input Voltage	V _{IL}	—	—	0.8	V	
Input Current	I _{IN}	-1.0 -10	— —	+1.0 +10	μA	0V ≤ V _{IN} ≤ V _{DD}
Output						
High Output Voltage	V _{OH}	V _{DD} – 0.025	—	—	V	DC Test
Low Output Voltage	V _{OL}	—	—	0.025	V	DC Test
Output Resistance	R _O	—	7 — 8 8	9 10 11 12	Ω	I _{OUT} = 10 mA, V _{DD} = 18V, T _A = +25°C 0°C ≤ T _A ≤ +70°C -40°C ≤ T _A ≤ +85°C -40°C ≤ T _A ≤ +125°C
Peak Output Current	I _{PK}	—	1.5	—	A	V _{DD} = 18V
Latch-Up Protection Withstand Reverse Current	I _{REV}	—	> 0.5	—	A	Duty cycle ≤ 2%, t ≤ 300 μsec V _{DD} = 18V
Switching Time (Note 1)						
Rise Time	t _R	—	25 — 29 30	35 40 40 40	ns	T _A = +25°C 0°C ≤ T _A ≤ +70°C -40°C ≤ T _A ≤ +85°C -40°C ≤ T _A ≤ +125°C, Figure 4-1
Fall Time	t _F	—	25 — 29 30	35 40 40 40	ns	T _A = +25°C 0°C ≤ T _A ≤ +70°C -40°C ≤ T _A ≤ +85°C -40°C ≤ T _A ≤ +125°C, Figure 4-1
Delay Time	t _{D1}	—	30 — 35 38	35 40 45 50	ns	T _A = +25°C 0°C ≤ T _A ≤ +70°C -40°C ≤ T _A ≤ +85°C -40°C ≤ T _A ≤ +125°C, Figure 4-1
Delay Time	t _{D2}	—	30 — 35 38	35 40 45 50	ns	T _A = +25°C 0°C ≤ T _A ≤ +70°C -40°C ≤ T _A ≤ +85°C -40°C ≤ T _A ≤ +125°C, Figure 4-1
Power Supply						
Power Supply Current	I _S	—	1.0 — 0.1	2.0 — 0.2	mA	V _{IN} = 3V (Both inputs) V _{IN} = 0V (Both inputs), V _{DD} = 18V

Note 1: Switching times ensured by design.

Note 2: Package power dissipation is dependent on the copper pad area on the PCB.

TC4426A/TC4427A/TC4428A

TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, all parameters apply with $4.5V \leq V_{DD} \leq 18V$.						
Parameters	Sym	Min	Typ	Max	Units	Conditions
Temperature Ranges						
Specified Temperature Range (C)	T_A	0	—	+70	°C	
Specified Temperature Range (E)	T_A	-40	—	+85	°C	
Specified Temperature Range (V)	T_A	-40	—	+125	°C	
Maximum Junction Temperature	T_J	—	—	+150	°C	
Storage Temperature Range	T_A	-65	—	+150	°C	
Package Thermal Resistances						
Thermal Resistance, 8L-6x5 DFN	θ_{JA}	—	33.2	—	°C/W	
Thermal Resistance, 8L-MSOP	θ_{JA}	—	206	—	°C/W	
Thermal Resistance, 8L-PDIP	θ_{JA}	—	125	—	°C/W	
Thermal Resistance, 8L-SOIC	θ_{JA}	—	155	—	°C/W	

TC4426A/TC4427A/TC4428A

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, over operating temperature range with $4.5V \leq V_{DD} \leq 18V$.



FIGURE 2-1: Rise Time vs. Supply Voltage.



FIGURE 2-4: Fall Time vs. Supply Voltage.



FIGURE 2-2: Delay Time vs. Input Amplitude.



FIGURE 2-5: Propagation Delay Time vs. Supply Voltage.



FIGURE 2-3: Rise and Fall Times vs. Temperature.



FIGURE 2-6: Propagation Delay Time vs. Temperature.

TC4426A/TC4427A/TC4428A

Note: Unless otherwise indicated, over operating temperature range with $4.5V \leq V_{DD} \leq 18V$.



FIGURE 2-7: High-State Output Resistance.



FIGURE 2-10: Low-State Output Resistance.



FIGURE 2-8: Supply Current vs. Frequency.



FIGURE 2-11: Supply Current vs. Capacitive Load.



FIGURE 2-9: Supply Current vs. Frequency.



FIGURE 2-12: Supply Current vs. Capacitive Load.

TC4426A/TC4427A/TC4428A

Note: Unless otherwise indicated, over operating temperature range with $4.5V \leq V_{DD} \leq 18V$.



FIGURE 2-13: Supply Current vs. Frequency.



FIGURE 2-15: Supply Current vs. Capacitive Load.



FIGURE 2-14: Quiescent Supply Current vs. Voltage.



FIGURE 2-16: Quiescent Supply Current vs. Temperature.

TC4426A/TC4427A/TC4428A

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

8-Pin PDIP/ MSOP/SOIC	8-Pin DFN	Symbol	Description
1	1	NC	No connection
2	2	IN A	Input A
3	3	GND	Ground
4	4	IN B	Input B
5	5	OUT B	Output B
6	6	V _{DD}	Supply input
7	7	OUT A	Output A
8	8	NC	No connection
—	PAD	NC	Exposed Metal Pad

Note 1: Duplicate pins must be connected for proper operation.

3.1 Inputs A and B

MOSFET driver inputs A and B are high-impedance, TTL/CMOS compatible inputs. These inputs also have 300 mV of hysteresis between the high and low thresholds that prevents output glitching, even when the rise and fall time of the input signal is very slow.

3.2 Ground (GND)

The ground pin is the return path for both the bias current and the high peak current that discharges the external load capacitance. The ground pin should be tied into a ground plane or have a very short trace to the bias supply source return.

3.3 Output A and B

MOSFET driver outputs A and B are low-impedance, CMOS push-pull style outputs. The pull-down and pull-up devices are of equal strength, making the rise and fall times equivalent.

3.4 Supply Input (V_{DD})

The V_{DD} input is the bias supply for the MOSFET driver and is rated for 4.5V to 18V, with respect to the ground pin. The V_{DD} input should be bypassed with local ceramic capacitors. The value of these capacitors should be chosen based on the capacitive load that is being driven.

3.5 Exposed Metal Pad

The exposed metal pad of the 6x5 DFN package is not internally connected to any potential. Therefore, this pad can be connected to a ground plane or other copper plane on a printed circuit board, to aid in heat removal from the package.

TC4426A/TC4427A/TC4428A

4.0 APPLICATIONS INFORMATION



FIGURE 4-1: Switching Time Test Circuit.

TC4426A/TC4427A/TC4428A

5.0 PACKAGING INFORMATION

5.1 Package Marking Information

8-Lead DFN



Example:



8-Lead MSOP



Example:



8-Lead PDIP (300 mil)



Example:



8-Lead SOIC (150 mil)



Example:



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

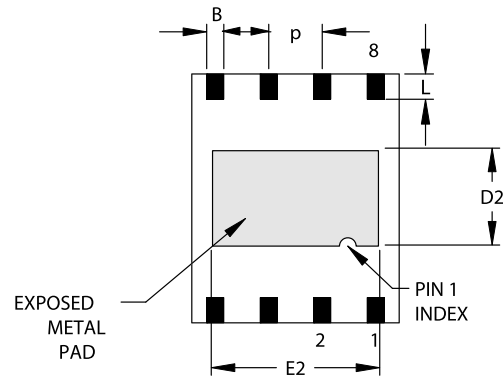
TC4426A/TC4427A/TC4428A

8-Lead Plastic Dual Flat No Lead Package (MF) 6x5 mm Body (DFN-S) – Saw Singulated

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



TOP VIEW



BOTTOM VIEW



Dimension Limits	Units	INCHES			MILLIMETERS*		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	P	.050 BSC			1.27 BSC		
Overall Height	A	.033	.035	.037	0.85	0.90	0.95
Package Thickness	A2	.031	.035	.037	0.80	0.89	0.95
Standoff	A1	.000	.0004	.002	0.00	0.01	0.05
Base Thickness	A3	.007	.008	.009	0.17	0.20	0.23
Overall Length	E	.195	.197	.199	4.95	5.00	5.05
Exposed Pad Length	E2	.152	.157	.163	3.85	4.00	4.15
Overall Width	D	.234	.236	.238	5.95	6.00	6.05
Exposed Pad Width	D2	.089	.091	.093	2.25	2.30	2.35
Lead Width	B	.014	.016	.019	0.35	0.40	0.47
Lead Length	L	.024		.026	0.60		0.65

Notes:

JEDEC equivalent: MO-220

Drawing No. C04-122

Revised 11/3/03

TC4426A/TC4427A/TC4428A

8-Lead Plastic Micro Small Outline Package (UA) (MSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n	8			8		
Pitch	P	.026 BSC			0.65 BSC		
Overall Height	A	-	-	.043	-	-	1.10
Molded Package Thickness	A2	.030	.033	.037	0.75	0.85	0.95
Standoff	A1	.000	-	.006	0.00	-	0.15
Overall Width	E	.193 TYP.			4.90 BSC		
Molded Package Width	E1	.118 BSC			3.00 BSC		
Overall Length	D	.118 BSC			3.00 BSC		
Foot Length	L	.016	.024	.031	0.40	0.60	0.80
Footprint (Reference)	F	.037 REF			0.95 REF		
Foot Angle	ϕ	0°	-	8°	0°	-	8°
Lead Thickness	c	.003	.006	.009	0.08	-	0.23
Lead Width	B	.009	.012	.016	0.22	-	0.40
Mold Draft Angle Top	α	5°	-	15°	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°	5°	-	15°

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187

Drawing No. C04-111

TC4426A/TC4427A/TC4428A

8-Lead Plastic Dual In-line (PA) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n	8			8		
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
 § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-018

TC4426A/TC4427A/TC4428A

8-Lead Plastic Small Outline (OA) – Narrow, 150 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n	8			8		
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff	§ A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057

6.0 REVISION HISTORY

Revision G (December 2012)

Added a note to each package outline drawing.

TC4426A/TC4427A/TC4428A

NOTES:

TC4426A/TC4427A/TC4428A

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	X	XX	XXX	X	Examples:
Device	Temperature Range	Package	Tape & Reel	PB Free	
Device:		TC4426A: 1.5A Dual MOSFET Driver, Inverting TC4427A: 1.5A Dual MOSFET Driver, Non-Inverting TC4428A: 1.5A Dual MOSFET Driver, Complementary			a) TC4426ACOA: 1.5A Dual Inverting MOSFET driver, 0°C to +70°C, 8LD SOIC package. b) TC4426AEOA: 1.5A Dual Inverting MOSFET driver, -40°C to +85°C, 8LD SOIC package. c) TC4426AEMF: 1.5A Dual Inverting MOSFET driver, -40°C to +85°C, 8LD DFN package.
Temperature Range:	C = 0°C to +70°C (PDIP & SOIC Only) E = -40°C to +85°C V = -40°C to +125°C				a) TC4427ACPA: 1.5A Dual Non-Inverting MOSFET driver, 0°C to +70°C, 8LD PDIP package. b) TC4427AEPA: 1.5A Dual Non-Inverting MOSFET driver, -40°C to +85°C, 8LD PDIP package. c) TC4427AVMF713: 1.5A Dual Non-Inverting MOSFET driver, -40°C to +125°C, 8LD DFN package, Tape and Reel.
Package:	MF = Dual, Flat, No-Lead (6X5 mm Body), 8-lead MF713 = Dual, Flat, No-Lead (6X5 mm Body), 8-lead (Tape and Reel) PA = Plastic DIP (300 mil Body), 8-lead OA = Plastic SOIC, (150 mil Body), 8-lead OA713 = Plastic SOIC, (150 mil Body), 8-lead (Tape and Reel) UA = Plastic Micro Small Outline (MSOP), 8-lead UA713 = Plastic Micro Small Outline (MSOP), 8-lead (Tape and Reel)				a) TC4428AEPA: 1.5A Dual Complementary MOSFET driver, -40°C to +85°C, 8LD PDIP package. b) TC4428ACOA713: 1.5A Dual Complementary MOSFET driver, 0°C to +70°C, 8LD SOIC package, Tape and Reel. c) TC4428AVMF: 1.5A Dual Complementary MOSFET driver, -40°C to +125°C, 8LD DFN package.

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Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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TC4426A/TC4427A/TC4428A

NOTES:

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ISBN: 9781620767986

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Fax: 86-21-5407-5066

China - Shenyang
Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen
Tel: 86-755-8864-2200
Fax: 86-755-8203-1760

China - Wuhan
Tel: 86-27-5980-5300
Fax: 86-27-5980-5118

China - Xian
Tel: 86-29-8833-7252
Fax: 86-29-8833-7256

China - Xiamen
Tel: 86-592-2388138
Fax: 86-592-2388130

China - Zhuhai
Tel: 86-756-3210040
Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore
Tel: 91-80-3090-4444
Fax: 91-80-3090-4123

India - New Delhi
Tel: 91-11-4160-8631
Fax: 91-11-4160-8632

India - Pune
Tel: 91-20-2566-1512
Fax: 91-20-2566-1513

Japan - Osaka
Tel: 81-66-152-7160
Fax: 81-66-152-9310

Japan - Yokohama
Tel: 81-45-471-6166
Fax: 81-45-471-6122

Korea - Daegu
Tel: 82-53-744-4301
Fax: 82-53-744-4302

Korea - Seoul
Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Kuala Lumpur
Tel: 60-3-6201-9857
Fax: 60-3-6201-9859

Malaysia - Penang
Tel: 60-4-227-8870
Fax: 60-4-227-4068

Philippines - Manila
Tel: 63-2-634-9065
Fax: 63-2-634-9069

Singapore
Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Hsin Chu
Tel: 886-3-5778-366
Fax: 886-3-5770-955

Taiwan - Kaohsiung
Tel: 886-7-213-7828
Fax: 886-7-330-9305

Taiwan - Taipei
Tel: 886-2-2508-8600
Fax: 886-2-2508-0102

Thailand - Bangkok
Tel: 66-2-694-1351
Fax: 66-2-694-1350

EUROPE

Austria - Wels
Tel: 43-7242-2244-39
Fax: 43-7242-2244-393

Denmark - Copenhagen
Tel: 45-4450-2828
Fax: 45-4485-2829

France - Paris
Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Munich
Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Italy - Milan
Tel: 39-0331-742611
Fax: 39-0331-466781

Netherlands - Drunen
Tel: 31-416-690399
Fax: 31-416-690340

Spain - Madrid
Tel: 34-91-708-08-90
Fax: 34-91-708-08-91

UK - Wokingham
Tel: 44-118-921-5869
Fax: 44-118-921-5820

11/27/12

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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